

REMARKS

Previously elected, and now allowed, method Claims 1 - 17 have been canceled leaving package structure Claims 18 - 20. In addition, new package structure Claims 21 - 24 have been added.

Applicants believe that the package structure claims herein presented are allowable over the art relied upon by the Examiner in the earlier prosecution of the now allowed method claims in Applicants' parent application.

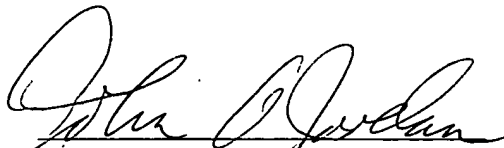
As stated by Applicants in their response to the Examiner's rejections of the now allowed method claims upon Tsai, et al. in view of Gonzales, et al., Tsai, et al. teach nothing whatsoever of attaching a passive SMD to a substrate, in the manner taught by Applicants. In addition, Tsai, et al. do not employ solder to attach their flip chip to a substrate, but rather use gold sharp-pointed studs on the substrate.

Accordingly, Applicants believe that the package structure claims presented herein are allowable over the art of record and, accordingly, respectfully request the Examiner to allow the claims, as presented, and pass the case to issue.

Respectfully submitted,

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